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Acceptability of Electronic Assemblies

Developed by



BUILD ELECTRONICS BETTER

participants from

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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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IPC-A-610H

Acceptability of Electronic Assemblies

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